Listing of claims

The listing of claims presented below will replace all prior versions, and listings, of claims in the application.

Listing of claims:

(NOTE: The Examiner agreed in an examiner interviews on January 11 and 27, 2006 that the following amendments to claims 1 and 3 overcome all standing rejections over the cited JP 10-268356 (Takebayashi) reference.):

1. **(currently amended)** A liquid crystal display device **having an active area having pixels for display** comprising:

a supporting column having an outer surface provided for an upper substrate and vertically extended from the upper substrate to a lower substrate so as to maintain a uniform cell gap therebetween;

a contact part provided for a common line disposed at a peripheral region outside ~~an~~ **the** active area of the lower substrate opposite to the upper substrate, wherein the contact part faces the supporting column at a corresponding position so as to guide electrical communication between the supporting column and the common line; and

an electrically conductive layer formed on the outer surfaces of the supporting column and on the upper substrate, wherein a portion of the electrically conductive layer on the supporting column is joined to the common line within the contact part so as to establish a signal interconnection between the lower substrate and the upper substrate.

2. (original) The liquid crystal display device of claim 1, wherein an insulating layer is further provided for the common line, and the contact part is a contact hole formed in the insulating layer so as to expose a portion of the common line.

3. **(currently amended)** A method for fabricating a liquid crystal display device

having an active area having pixels for display, comprising:

providing a supporting column having an outer surface for an upper substrate, wherein the supporting column is vertically extended from the upper substrate to a lower substrate so as to maintain a uniform cell gap between the outer surface of the upper substrate and the lower substrate;

forming an electrically conductive layer on the outer surface of the supporting column and on the upper substrate;

providing a contact part for a common line disposed at a peripheral region outside ~~an~~ **the** active area of the lower substrate confronting the upper substrate, wherein the contact part faces the supporting column at a corresponding position; and

uniting the lower substrate and the upper substrate so that a portion of the electrically conductive layer on the supporting column is joined to the common line within the contact part, thereby establishing a signal interconnection between the lower substrate and the upper substrate.

4. (original) The method of claim 3, wherein the providing of the contact part includes providing an insulating layer for the common line and forming a contact hole in the insulating layer so as to expose a portion of the common line.

5. (original) The method of claim 3, wherein the electrically conductive layer includes an indium tin oxide (ITO) layer.